

Product Summary

BV _{DSS}	R _{DS(ON)} MAX	I _D MAX T _C = +25°C
-20V	6mΩ @ V _{GS} = -4.5V	-90A
	8mΩ @ V _{GS} = -2.5V	-78A

Description

This new generation MOSFET is designed to minimize R_{DS(ON)} and yet maintain superior switching performance. This device is ideal for use in Notebook battery power management and load switch.

Applications

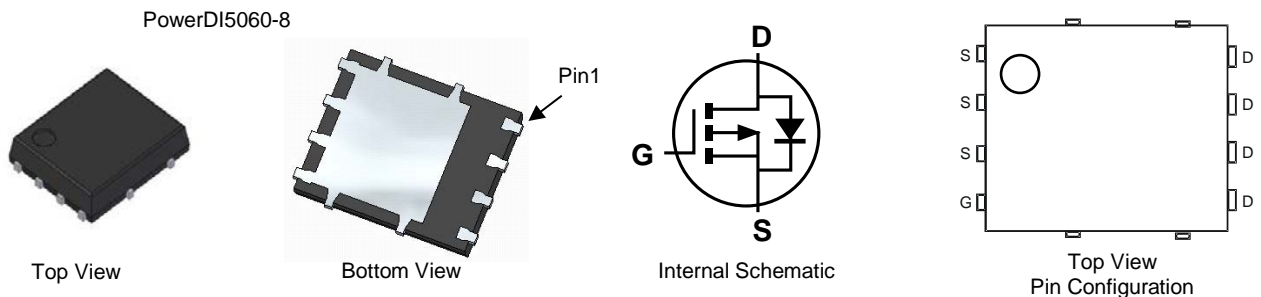
- Load Switch
- Power Management Functions

Features

- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} – Minimizes On State Losses
- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application
- <1.1mm Package Profile – Ideal for Thin Applications
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. “Green” Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

Mechanical Data

- Case: PowerDI[®] 5060-8
- Case Material: Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Lead-frame; Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Weight: 0.097 grams (Approximate)

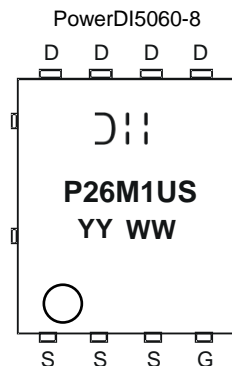


Ordering Information (Note 4)

Part Number	Case	Packaging
DMP26M1UPS-13	PowerDI5060-8	2,500 / Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



= Manufacturer's Marking
 P26M1US = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Two Digits of Year (ex: 20 = 2020)
 WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 10	V
Continuous Drain Current, $V_{GS} = -10\text{V}$ (Note 7)	I_D	$T_C = +25^\circ\text{C}$	-90
		$T_C = +70^\circ\text{C}$	-72
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)	I_{DM}	-360	A
Maximum Continuous Body Diode Forward Current (Note 6)	I_S	-4.5	A
Pulsed Body Diode Forward Current (10 μs Pulse, Duty Cycle = 1%)	I_{SM}	-360	A
Avalanche Current, $L = 0.1\text{mH}$ (Note 8)	I_{AS}	-30	A
Avalanche Energy, $L = 0.1\text{mH}$ (Note 8)	E_{AS}	47	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	1.34	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	Steady State	93
Total Power Dissipation (Note 6)		P_D	2.76
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	Steady State	45
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	1.7
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	-20	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	-1	μA	$V_{DS} = -16\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 8\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.4	—	-1	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	5	6	m Ω	$V_{GS} = -4.5\text{V}, I_D = -15\text{A}$
		—	6.2	8		$V_{GS} = -2.5\text{V}, I_D = -10\text{A}$
Diode Forward Voltage	V_{SD}	—	-0.54	-1.1	V	$V_{GS} = 0\text{V}, I_S = -1\text{A}$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{iss}	—	5392	—	pF	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	608	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	564	—	pF	
Gate Resistance	R_g	—	2.05	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = -4.5\text{V}$)	Q_g	—	75	—	nC	$V_{DS} = -10\text{V}, I_D = -20\text{A}$
Total Gate Charge ($V_{GS} = -10\text{V}$)	Q_g	—	164	—	nC	
Gate-Source Charge	Q_{gs}	—	6.9	—	nC	
Gate-Drain Charge	Q_{gd}	—	19.8	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	9	—	ns	$V_{DD} = -10\text{V}, V_{GEN} = -4.5\text{V},$ $R_{GEN} = 1\Omega, I_D = -10\text{A}$
Turn-On Rise Time	t_R	—	24	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	69	—	ns	
Turn-Off Fall Time	t_F	—	107	—	ns	
Reverse Recovery Time	t_{RR}	—	54	—	ns	$I_F = -10\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge	Q_{RR}	—	55	—	nC	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 - Thermal resistance from junction to soldering point (on the exposed drain pad).
 - I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

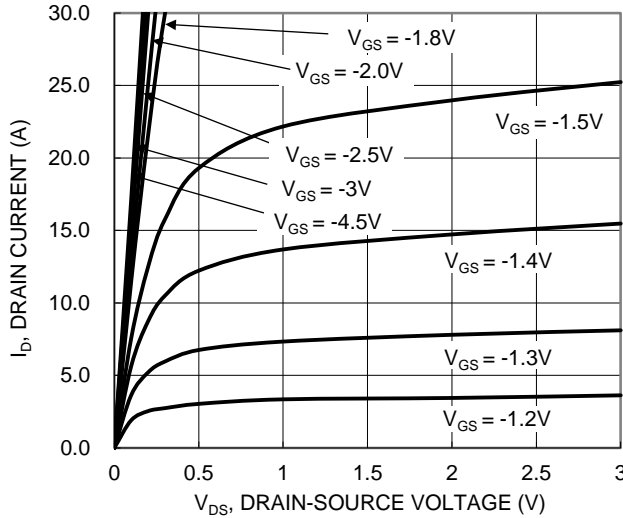


Figure 1. Typical Output Characteristic

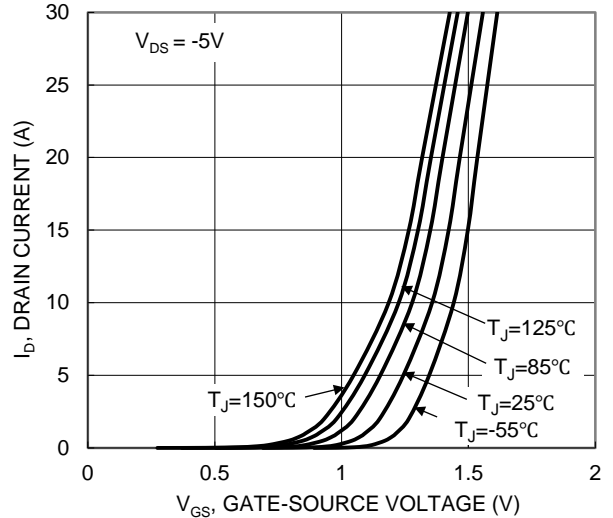


Figure 2. Typical Transfer Characteristic

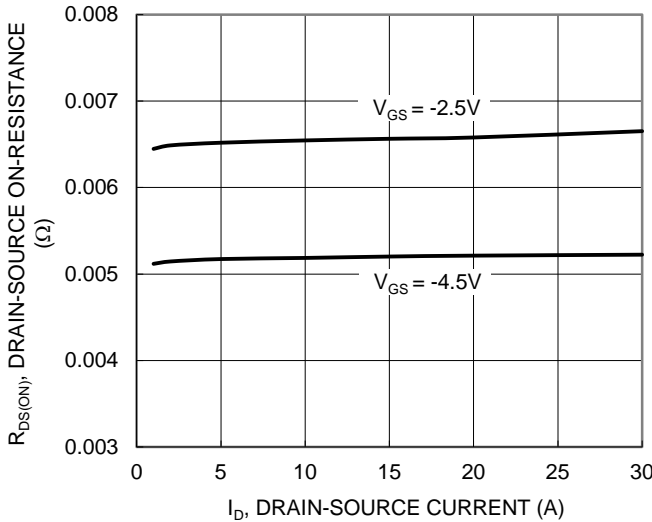


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

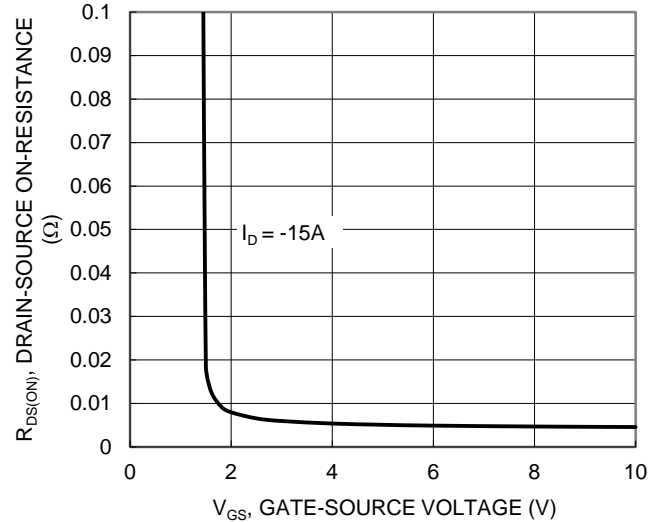


Figure 4. Typical Transfer Characteristic

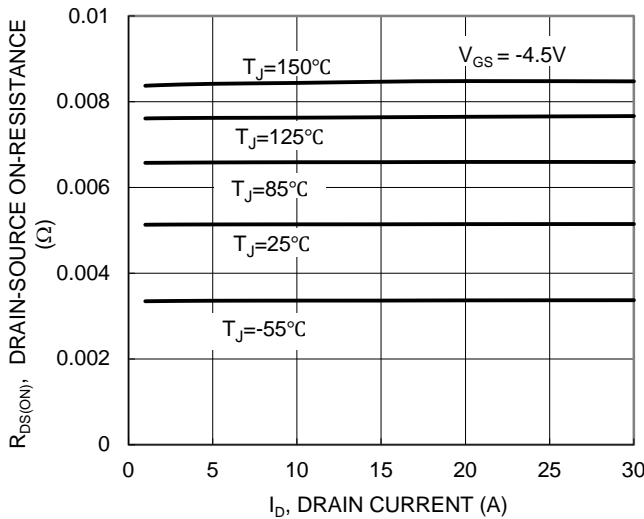


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

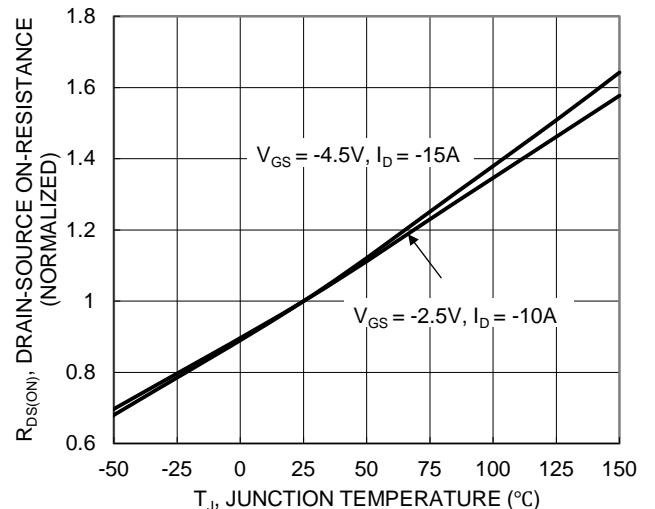


Figure 6. On-Resistance Variation with Junction Temperature

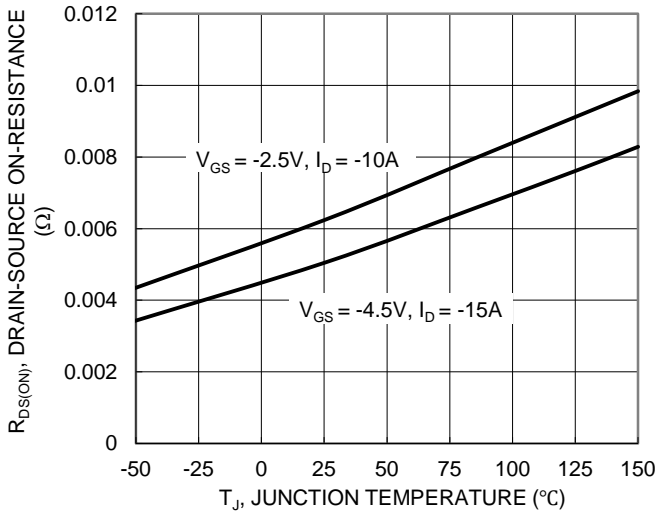


Figure 7. On-Resistance Variation with Junction Temperature

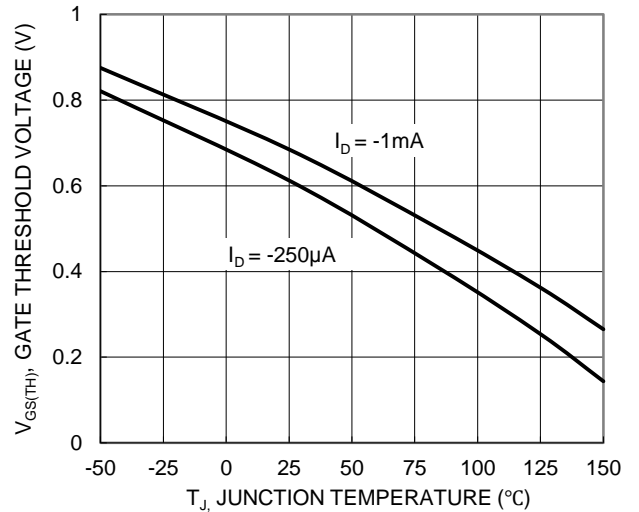


Figure 8. Gate Threshold Variation vs. Junction Temperature

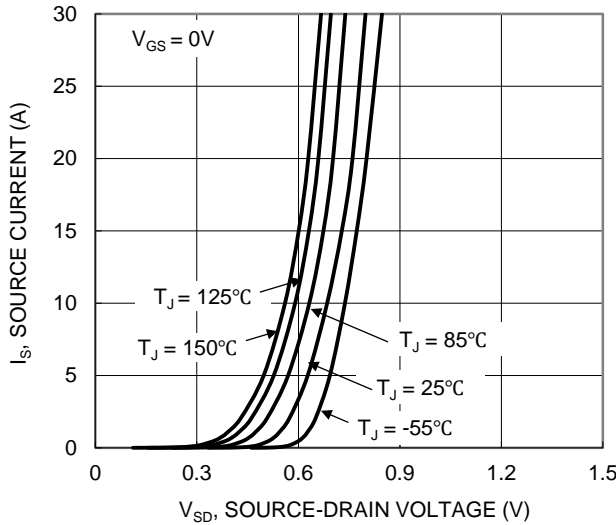


Figure 9. Diode Forward Voltage vs. Current

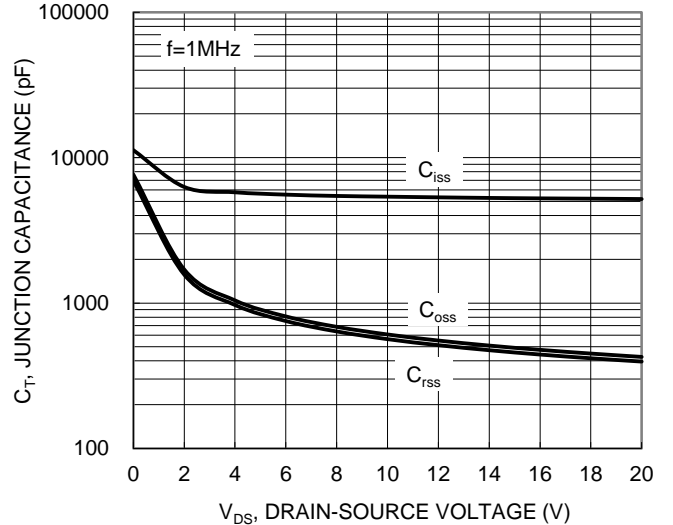


Figure 10. Typical Junction Capacitance

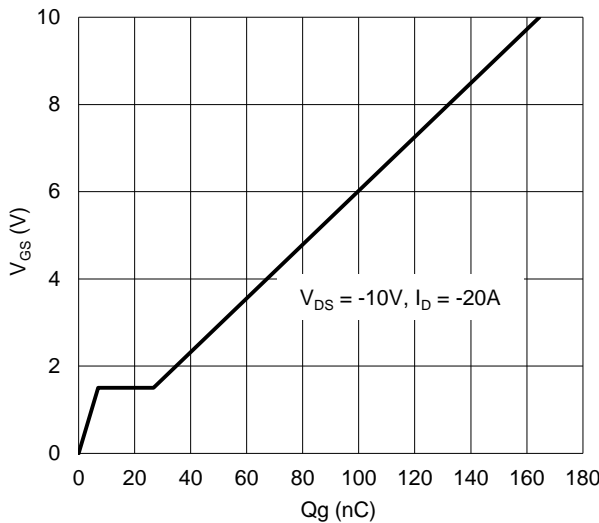


Figure 11. Gate Charge

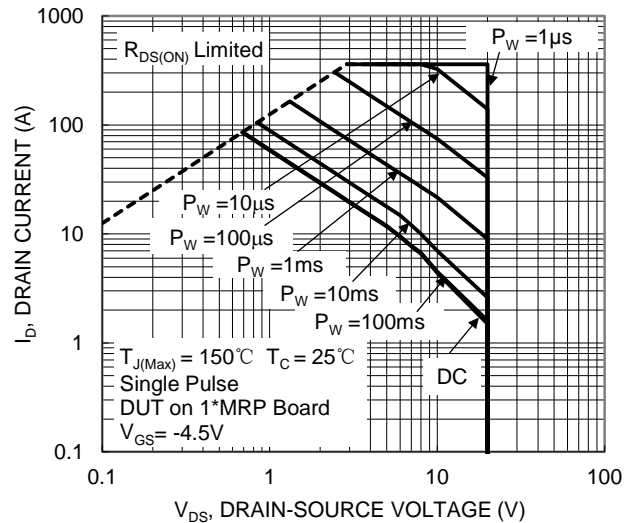


Figure 12. SOA, Safe Operation Area

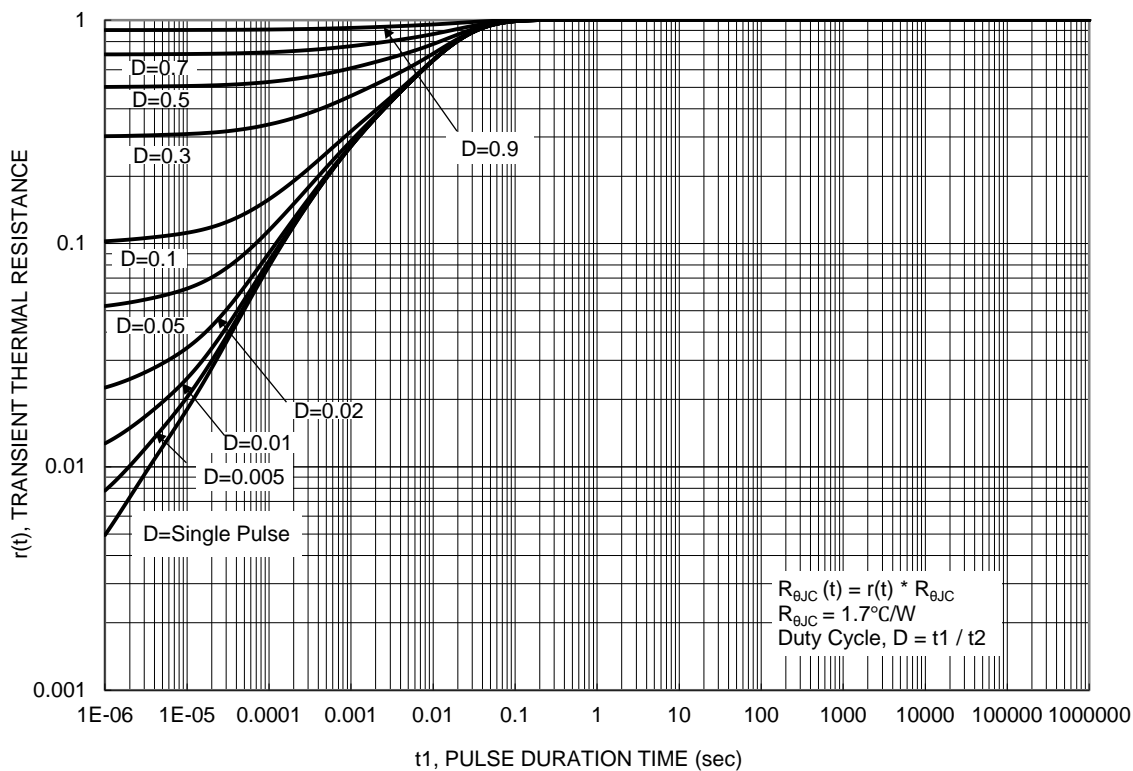
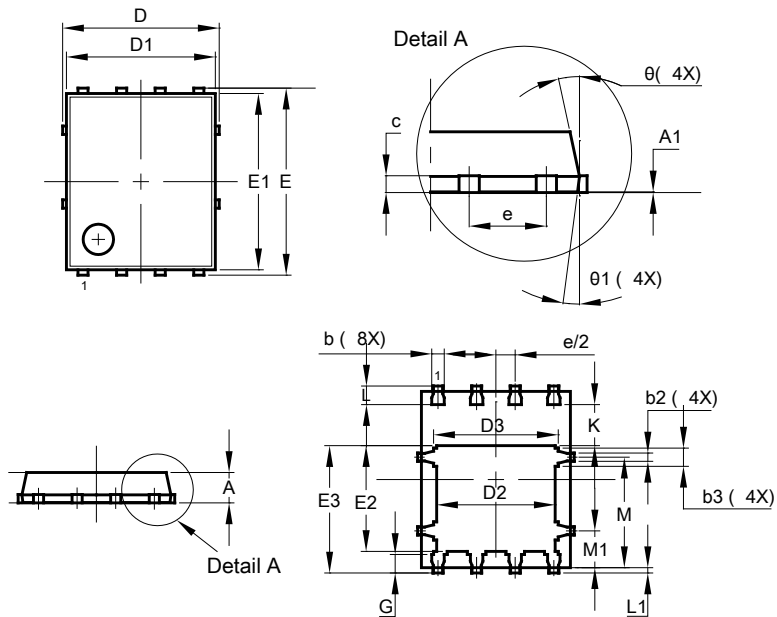


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

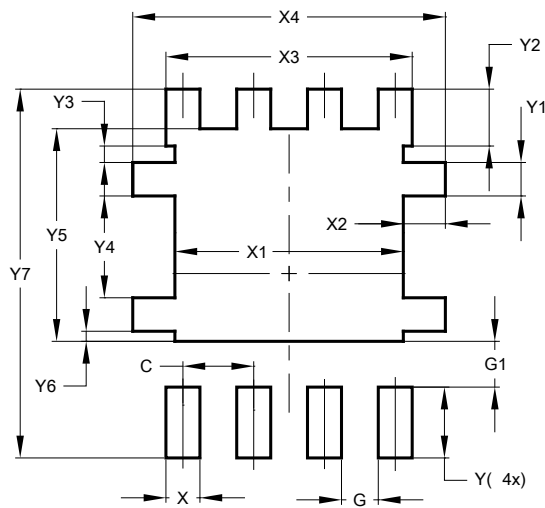
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



PowerDI5060-8			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	-
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.40	0.80	0.60
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.70	4.10	3.90
D3	3.90	4.30	4.10
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E3	3.99	4.39	4.19
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	-	-
L	0.51	0.71	0.61
L1	0.100	0.200	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
θ	10°	12°	11°
θ_1	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
X3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

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